PATENT ABSTRACTS OF JAPAN

(11)Publication number:

63-047961

(43) Date of publication of application: 29.02.1988

(51)Int.CI.

H01L 23/50 H01L 23/12

H01L 25/04

(21)Application number: 61-193105

(71)Applicant: MITSUBISHI ELECTRIC CORP

(22)Date of filing:

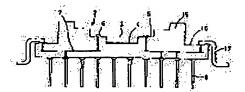
18.08.1986

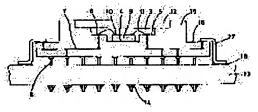
(72)Inventor: NAKAO SHIN

(54) SEMICONDUCTOR PACKAGE

(57)Abstract:

PURPOSE: To be able to improve the packaging density of semiconductor elements without increasing the size of a whole semiconductor package as the conventional one by leading out input/output leads for electrically connecting the semiconductor element to the exterior of the package from the side surface of the package. CONSTITUTION: Input/output leads 17 led from the side surface of a semiconductor package which contains a semiconductor element 9 and has input/output pins 8 on the rear surface for electrically connecting the element 9 to the exterior of the semiconductor package are provided on the semiconductor package. For example, a step 16 is formed on the side surface of the periphery of a package substrate 15, and a plurality of the leads 17 for electrically connecting the element 9 contained in the substrate 15 to the exterior of the substrate 15 are led from the step 16 at predetermined pitches. A bonding pad 6 is electrically connected to the pins 8 and the leads 17 by wirings 7 in the substrate 15.





LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office